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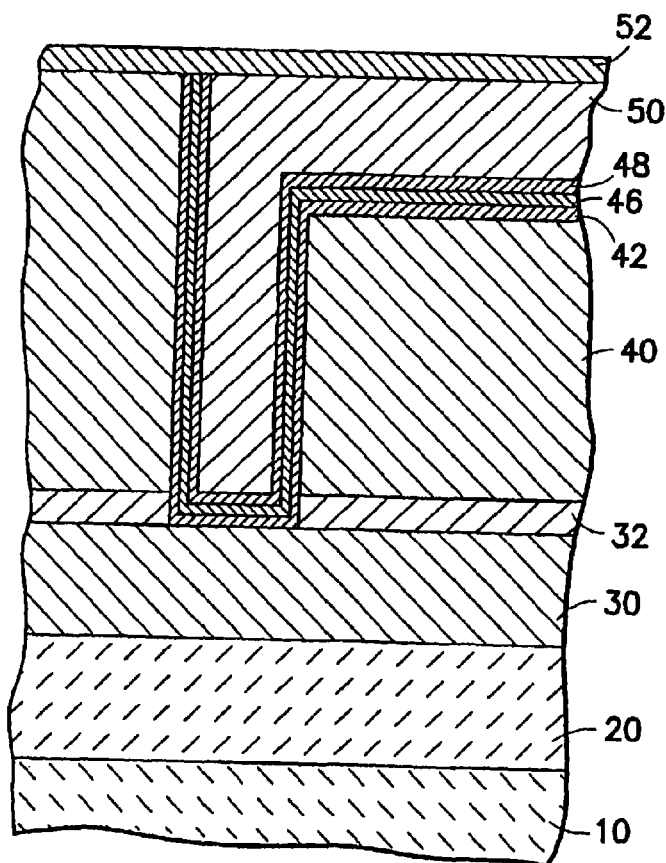
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(54) Title: CHROMIUM ADHESION LAYER FOR COPPER VIAS IN LOW-K TECHNOLOGY



(57) Abstract: In integrated circuits having copper interconnect (30, 50) and low-k interlayer dielectrics (40), a problem of open circuits after heat treatment was discovered and solved by the use of a first liner layer of Cr (42), followed by a conformal liner layer of CVD TiN (46), followed in turn by a final liner layer of Ta or TaN (48), thus improving adhesion between the via (50) and the underlying copper layer (30) while maintaining low resistance.



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